

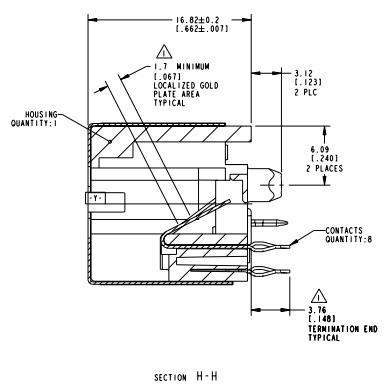
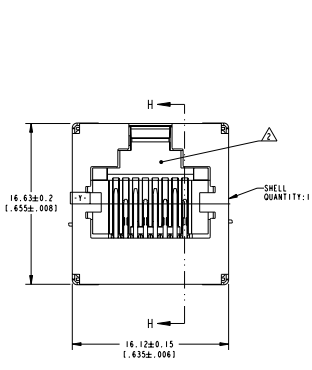
REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
E		REVISED PER EC 0511-0019-03	DMARRAS	DD	BA
F		EC0513-0069-05	JROCKMAN	LAN	JW
G		EC0516-021711	JROCKMAN	LAN	JW
H		ECR-10-007045	TUMBER	KS	ST

D

C

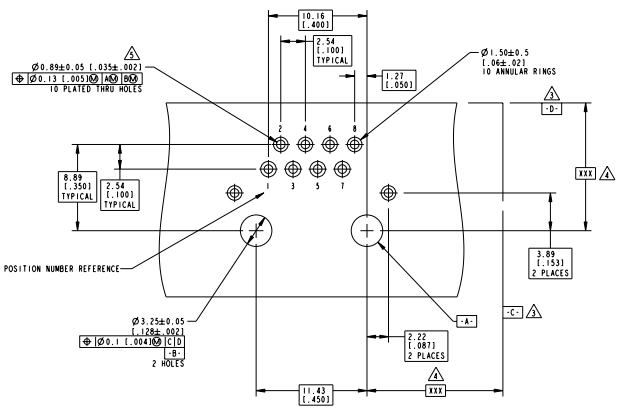
B

A

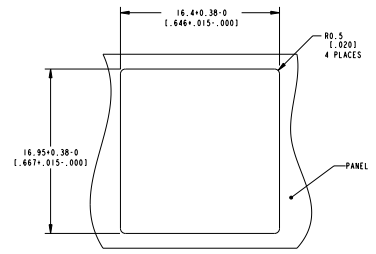
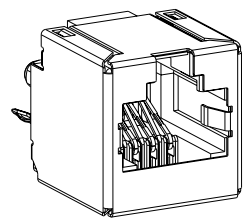


SECTION H-H

- MATERIAL: HOUSING - LCP, COLOR: SEE TABLE
 - TERMINALS: 0.30mm (.012) THICK PHOS BRONZE PLATED WITH 1.27µm (0.00050) MINIMUM HARD GOLD IN LOCALIZED AREA AND 2.53µm (0.00080) MINIMUM TIN-LEAD IN SOLDER AREA OVER 1.27µm (0.00050) MINIMUM NICKEL UNDERPLATE.
 - SHIELD: 0.25mm (.010) THICK COPPER ALLOY PLATED WITH 2.53µm (0.00080) MINIMUM THICK BRIGHT TIN OVER 1.27µm (0.00050) MINIMUM NICKEL.
- △ CAVITY CONFORMS TO FCC 47 CFR 48 PART F.
 - △ DATUMS ESTABLISHED BY CUSTOMER.
 - △ DIMENSIONS ESTABLISHED BY CUSTOMER.
 - △ DRILLED HOLE DIAMETER 1.02±0.03mm (.040±.001). COPPER THK 0.23±0.08mm (.009). TIN LEAD THICKNESS 8µm (.000315) MIN.
 - △ PC BOARDS GREATER THAN 1.57mm (.062) IN THICKNESS MAY REQUIRE SPECIAL EXTRACTION TOOLING, CONSULT ENGINEERING.



RECOMMENDED
 PRINTED CIRCUIT BOARD
 LAYOUT
 RECOMMENDED PRINTED CIRCUIT BOARD
 THICKNESS 1.41 (0.055) MIN
 COMPONENT SIDE OF PRINTED CIRCUIT BOARD



RECOMMENDED
 PANEL CUTOUT

NATURAL	1116202-2
supersede by 6116202-1	-BluCR-1116202-1
HOUSING COLOR	PART NUMBER

DATE	06MAY99	DESIGNER	DMARRAS	DATE	06MAY99
BY	DMARRAS	REVISED BY	DMARRAS	REVISED DATE	06MAY99
DESCRIPTION	MODULAR JACK ASSEMBLY, VERTICAL, COMPLIANT P10, SHIELDED, 8 POSITION, CATEGORY 5				
SCALE	1:1	STANDARD	ASME Y14.5	REVISED	1116202
PROJECT	1116202	CUSTOMER DRAWING			